



XXXIII Cycle

# **CMOS** distributed signal processing systems for radiation sensors Andrea Di Salvo Supervisor: Prof. Angelo Rivetti

### **Research context and motivation**

- There are two kind of radiation detectors in High Energy Physics (HEP) experiments. In monolithic pixel sensors, the electronic shares the same die of the active pixel, while in the **hybrid** solution the implemented electronic is decoupled from the sensor.
- A standard readout system requires **multichannel** architecture (typically 10–100 channels), 8-12 bits of resolution, up to 160 MS/s, low-power consumption and radiation harness feature.
- Furthermore, both amplitude time and measurements are required to properly identify the event source.



Sensor

## **Novel contributions**

- A single-channel prototype was submitted in 110 nm CMOS technology with four metal layers available. This run will allow to test both the injection system and the calibration engine.
- The efforts concerned the physical implementation of the algorithm and its integration with the other blocks. The original method was simplify using:
  - 32 bit fixed point representation, **Q(12.20)**.
- 12 bits 20 bits

- Programmable learning parameters to adapt the algorithm to different ADC-scenarios.





#### Addressed research questions/problems

After the acquisition from the sensors, the signal have to be processed by an amplification stage, then it must be digitized through an Analog-to-Digital Converter (ADC).



 The explored architecture is a fully differential Successive Approximation Register (SAR) ADC. The nominal resolution is **12 bits**. During the conversion process could occur a data loss (**missing codes**) due to the non-linearity of the system.

ADC

Signal

processing

In order to solve this lack, it is possible to implement a **calibration circuit** on-chip. The technique adopted for this work is named **Offset Double Conversion** (ODC). It is based on the superposition principle and an offset injection.

A sample is converted twice. The first time is added the analog offset, in the second one is subtracted the same quantity. Thus, a dedicated circuit provides the double injection.



Taking into account the offset, the subtraction of these two quantities gives an exstimation of the conversion error. This deviation can be corrected using a suitable array of weights.



• Moreover, due to their environment applications, these devices can suffer from a Single Event **Upset** (SEU). Indeed the interaction of a particle could deposit a local charge inside the silicon substrate, then a bit-flip can occur in a register. • The last stage involves a Digital Signal Processing (DSP) block to process the incoming data.



• Furthermore, a study about the **performance** of the algorithm was carried out. This analysis could be useful in a future upgrade of the test-chip to save more area, power and calibration time.

# Adopted methodologies



 The yellow boxes highlight the digital domain of the test chip. The smaller boxes are two serializers (one of which is configurable), the larger one is the **calibration** engine. Inside the correction block was accomodate a **slow-control** coupled to another dedicated serializer to write and read the most important registers.

The main efforts has been done for the implementation of the scripts. The synthesis was performed using Design Compiler. IC Compiler II was adopted to complete the Place & Route phase. The functionality were tested with PrimeTime and Questa.

	Calibration	Raw serializer	Configurable serializer
Clock (ns)	25	5	5



The DSP stage should basically perform a **filter action** to reduce the noise on the sampled data. Depending on the signal shape, a **compression algorithm** could also required. It is also desirable a real-time **spectrum analysis** to perform a Fast Fourier Transform (FFT).

#### **External training activities**

- XXVII Giornate di studio sui rivelatori Scuola F. Bonaudi, Cogne (AO), 12-16 February 2018 (25 h).
- Efficient Machine Learning for IoT, EPFL (Switzerland), 23-24 August 2018 (12 h).
- VIII International Course "Detectors and Electronics for High Energy Physics, Astrophysics, Space Applications and Medical Physics", INFN National Laboratories of Legnaro (PD), 1-5 April 2019 (30 h).
- Essential verification with System Verilog and UVM, Europractice training course, imec, Leuven (Belgium), 30 September 4 October 2019.

### Submitted and published works

- Ciciriello, F.; Marzocca, C.; Demaria, L.; Pacher, L.; Rotondo, F.; Wheadon, R.; Di Salvo, A.; Mazzucchelli, P., "A Rad-Hard 12*bit Auto-Calibrated ADC in CMOS 65nm*", 2017 IEEE Nuclear Science Symposium and Medical Imaging Conference (NSS/MIC), IEEE, 2017.
- G. Baruffa, P. Placidi, A. Di Salvo, S. Marconi and A. Paternò, "An Improved Algorithm for On-Chip Clustering and Lossless Data Compression of HL-LHC Pixel Hits", poster accepted at IEEE 2018 NSS/MIC/RTSD, Sydney, 10–17 November 2018.
- A. Di Salvo, "Design of a 12-bit SAR ADC with digital self-calibration for radiation detectors front-ends", 15th Conference on Ph.D. Research in Microelectronics and Electronics, PRIME 2019, Lausanne (Switzerland), 15-18 July 2019.
- R. A. Giampaolo, A. Di Salvo, L. Pancheri, T. Croci, J. Olave, A. Rivetti, M. Da Rocha Rolo, S. Mattiazzo, P. Giubilato, "Depleted MAPS on a 110 nm CMOS CIS Technology", 26th IEEE International Conference on Electronics Circuits and Systems, Genova, Italy, 27-29 November 2019 [in press].

Area (µm²)	664x1064	72x92	72x126
Power (mW)	0.61	0.0086	0.1234

#### **Future work**

- **Testing** and **debugging** of the chip (available in December 2019).
- Completing the acquisition chain with the **DSP block**.
- Applying **radiation protection** to the registers.

#### List of attended classes

- 01SHCRV Unsupervised neural networks (didattica di eccellenza) (09/04/2018, 6)
- 01QORRV Writing Scientific Papers in English (21/02/2018, 3)
- 01SFTRV Fondamenti probabilistici e visione nella robotica di servizio (12/06/2018, 4)
- 01RISRP Public speaking (31/08/2018, 1)
- 01QEZRV Sviluppo e gestione di sistemi di acquisizione dati (29/11/2018, 5)
- 01QSCIU Reconfigurable computing (11/02/2019, 4)
- 02LWHRV Communication (14/03/2019, 1)
- 01SHMRV Entrepreneurial Finance (14/03/2019, 1)
- 03QTIIU Mimetic learning (08/07/2019, 4)
- 03QRHRV Microelectronics for radiation detection II (03/06/2019, 4)
- 03LCLRV Epistemologia della macchina (20/06/2019, 4)





#### **Electrical, Electronics and**

#### **Communications Engineering**